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## Intel Platform Memory Operations

### DDR3L/RS 1600 Memory Down Validation Results

Listed below are the results from a small sample of DDR3L/RS 1600 DRAMs tested on Intel reference mobile platforms based on 4th Gen Intel® Core™ Processor based on Mobile U-Processor Line (codename Haswell). We are providing this information as a guide to module performance with Intel® reference platforms. This testing is not intended to replace the normal OEM component qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

DRAM DDR3L/RS 1600 (Memory Down)										Updated/ New Parts
DRAM										IDD6 (typical)
Supplier	Part Number	Package Density	Density Die	Package	Width	Die Revision	Date Code	Tested Speed	Reduced Standby	25C
Elpida	EDJ4216EFBG-GNL-F	4Gb	4Gb	SDP	x16	F	1251	1600 CL11	<b>Yes</b>	2.2 (mA)
Elpida	EDJ4216EFBG-GN-F	4Gb	4Gb	SDP	x16	F	1228	1600 CL11	No	N/A
Elpida	EDJ8416E6MB-GNL-F	8Gb	4Gb	DDP	x16	F	1306	1600 CL11	<b>Yes</b>	4.4(mA)
Elpida	EDJ8416E6MB-GN-F	8Gb	4Gb	DDP	x16	F	1247	1600 CL11	No	N/A
Micron	MT41K256M16HA-125 M:E	4Gb	4Gb	SDP	x16	E	1242	1600 CL11	<b>Yes</b>	3.5 (mA)
Micron	MT41K256M16HA-125:E	4Gb	4Gb	SDP	x16	E	1222	1600 CL11	No	N/A
Micron	MT41K512M16TNA-125M:E	8Gb	4Gb	DDP	x16	E	1248	1600 CL11	<b>Yes</b>	7(mA)
Micron	MT41K512M16TNA-125 :E	8Gb	4Gb	DDP	x16	E	1304	1600 CL11	No	N/A
Samsung	K4B4G1646B-HYK0	4Gb	4Gb	SDP	x16	B	1310	1600 CL11	No	N/A
Samsung	K4B4G1646Q-HYK0	4Gb	4Gb	SDP	x16	Q	1349	1600 CL11	No	N/A
Samsung	K4B4G1646Q-HKK0	4Gb	4Gb	SDP	x16	Q	1349	1600 CL11	<b>Yes</b>	2.4 (mA)
Samsung	K4B8G1646Q-MYK0	4Gb	8Gb	DDP	x16	Q	1349	1600 CL11	No	N/A
SK hynix	H5TC4G63AFR-PBR	4Gb	4Gb	SDP	x16	A	1246	1600 CL11	<b>Yes</b>	2.4 (mA)
SK hynix	H5TC4G63AFR-PBA	4Gb	4Gb	SDP	x16	A	1234	1600 CL11	No	N/A

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**DRAM DDR3L/RS 1600 (Memory Down)**

<b>DRAM</b>										<b>IDD6 (typical)</b>
Supplier	Part Number	Package Density	Density Die	Package	Width	Die Revision	Date Code	Tested Speed	Reduced Standby	25C
SK hynix	H5TC8G63AMR-PBR	8Gb	4Gb	DDP	x16	A	1318	1600 CL11	Yes	4.8(mA)
SK hynix	H5TC8G63AMR-PBA	8Gb	4Gb	DDP	x16	A	1304	1600 CL11	No	N/A

Updated on April 1, 2014